

PMEG2005CT-Q

20 V, 500 mA low VF dual Schottky barrier rectifier

Product data sheet

1. General description

Planar Schottky barrier rectifier in common cathode configuration with an integrated guard ring for stress protection, encapsulated in a SOT23 small Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: I_{F(AV)} ≤ 0.5 A
- Reverse voltage: V_R ≤ 20 V
- · Small SMD plastic package
- Low forward voltage
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Low voltage rectification
- Reverse polarity protection
- · High efficiency DC-to-DC conversion
- · High-speed switching
- Switch Mode Power Supply (SMPS)
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode				•	'		
V _R	reverse voltage	T _j = 25 °C		-	-	20	V
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{amb} \le$ 100 °C	[1]	-	-	0.5	Α
		δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 130 °C		-	-	0.5	А
V _F	forward voltage	I _F = 0.5 A; T _j = 25 °C		-	360	390	mV
I _R	reverse current	V _R = 20 V; T _j = 25 °C		-	30	200	μΑ

[1] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	Α	anode (diode 1)]3	K1; K2
2	Α	anode (diode 2)		
3	K1, K2	common cathode (diode 1 and diode 2)	SOT23	A1 A2 006aaa438

6. Ordering information

Table 3. Ordering information

Type number	Package							
	Name	Description	Version					
PMEG2005CT-Q		plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body	SOT23					

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
PMEG2005CT-Q	P8%

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode						
V _R	reverse voltage	T _j = 25 °C		-	20	V
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{amb} \le$ 100 °C	[1]	-	0.5	А
		δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 130 °C		-	0.5	A
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ ms}; \delta \le 0.25$		-	3.9	А
I _{FSM}	non-repetitive peak forward current	t_p = 8 µs; square wave; $T_{j(init)}$ = 25 °C		-	10	А
Per device;	one diode loaded		_			
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[2]	-	330	mW
			[3]	-	400	mW
			[1]	-	460	mW
T _j	junction temperature			-	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C

- [1] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1cm².

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit		
Per device; one	Per device; one diode loaded								
R _{th(j-a)}	thermal resistance from junction to ambient		[1] [2]	-	-	375	K/W		
			[1] [3]	-	-	310	K/W		
			[1] [4]	-	-	270	K/W		
R _{th(j-sp)}	thermal resistance from junction to solder point		[5]	-	-	60	K/W		

^[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

^[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

^[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

^[5] Soldering point of cathode tab.

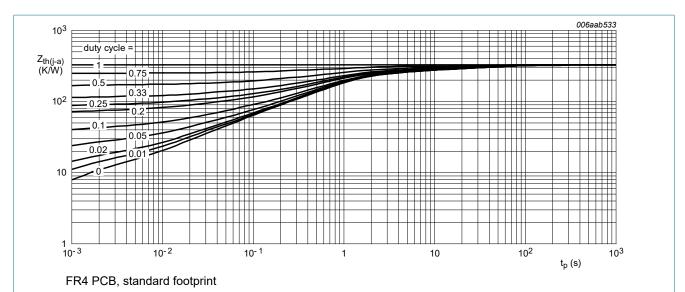


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

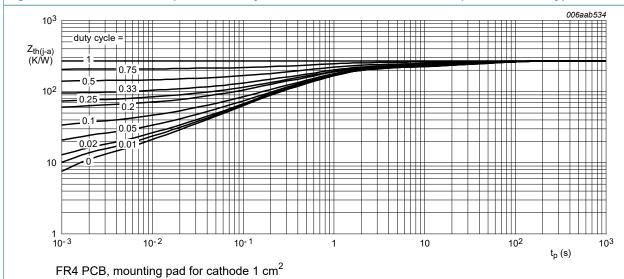


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

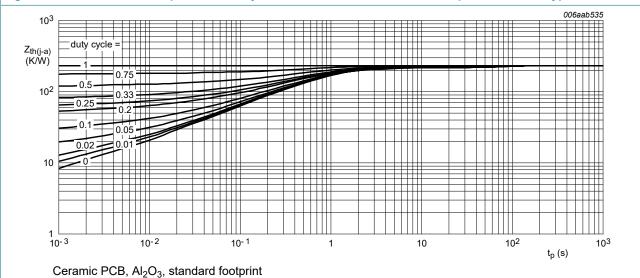


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Per diode	'				'	
V _F	forward voltage	I _F = 0.1 mA; T _j = 25 °C	-	95	130	mV
		I _F = 1 mA; T _j = 25 °C	-	155	190	mV
		I _F = 10 mA; T _j = 25 °C	-	215	240	mV
		I _F = 100 mA; T _j = 25 °C	-	285	330	mV
		I _F = 0.5 A; T _j = 25 °C	-	360	390	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	-	11	40	μΑ
		V _R = 20 V; T _j = 25 °C	-	30	200	μΑ
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C	-	66	80	pF
t _{rr}	reverse recovery time	When switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω ; measured at I_R = 1 mA.	-	22	-	ns

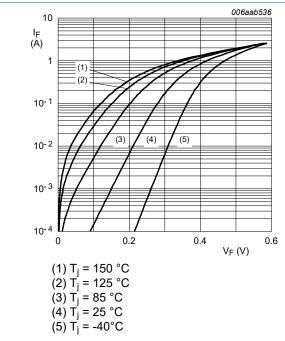
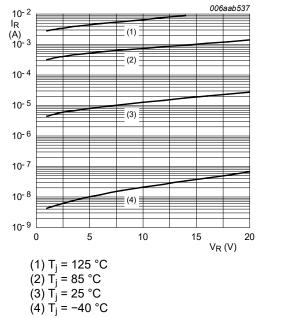


Fig. 4. Forward current as a function of forward voltage; typical values



(4) $I_j = -40$ °C Fig. 5. Reverse current as a function of reverse

voltage; typical values

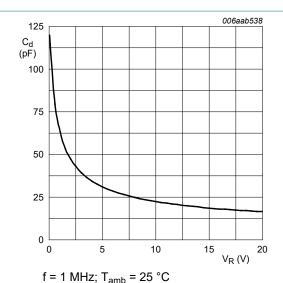
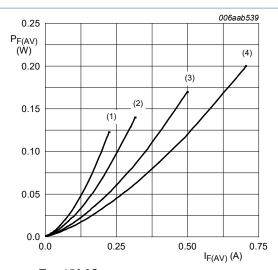
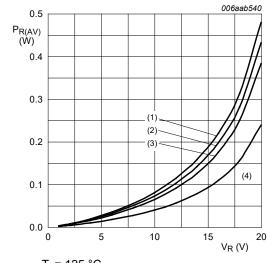


Fig. 6. Diode capacitance as a function of reverse voltage; typical values



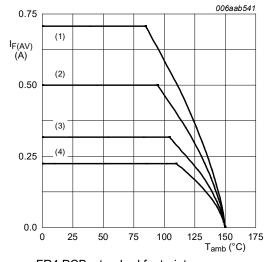
 $T_j = 150 \,^{\circ}\text{C}$ (1) $\delta = 0.1$ (2) $\delta = 0.2$ (3) $\delta = 0.5$ (4) $\delta = 1$

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 125 \,^{\circ}\text{C}$ (1) $\delta = 1$ (2) $\delta = 0.9$ (3) $\delta = 0.8$ (4) $\delta = 0.5$

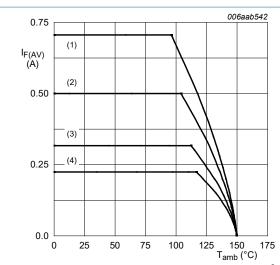
Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint $T_j = 150 \,^{\circ}\text{C}$ (1) $\delta = 1$; DC (2) $\delta = 0.5$; $f = 20 \,\text{kHz}$

(3) $\delta = 0.2$; f = 20 kHz(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

 $T_i = 150 \, ^{\circ}C$

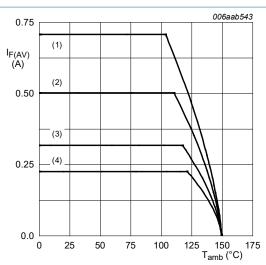
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint

T_i = 150 °C

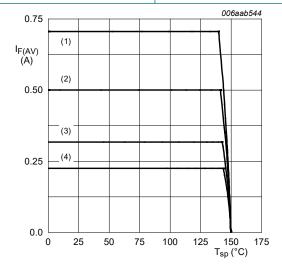
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



T_i = 150 °C

 $(1) \delta = 1; DC$

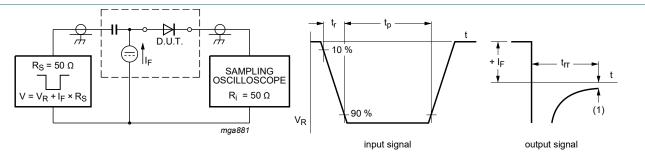
(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

11. Test information



(1) $I_R = 1 \text{ mA}$

Input signal: reverse pulse rise time t_r = 0.6 ns; reverse voltage pulse duration t_p = 100 ns; duty cycle δ = 0.05 Oscilloscope rise time t_r = 0.35 ns

Fig. 13. Reverse recovery time: test circuit and waveforms

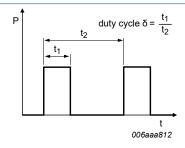


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

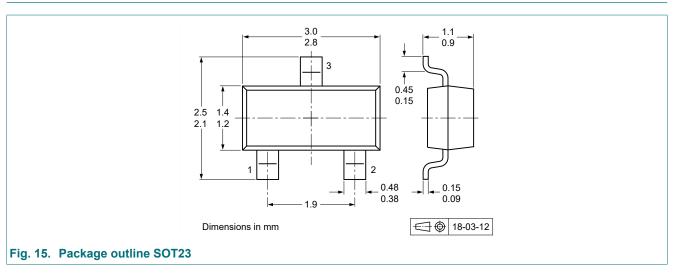
 $I_{RMS} = I_{F(AV)}$ at DC

 $I_{RMS} = I_{M} \times \sqrt{\delta}$ with I_{RMS} defined as RMS current

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

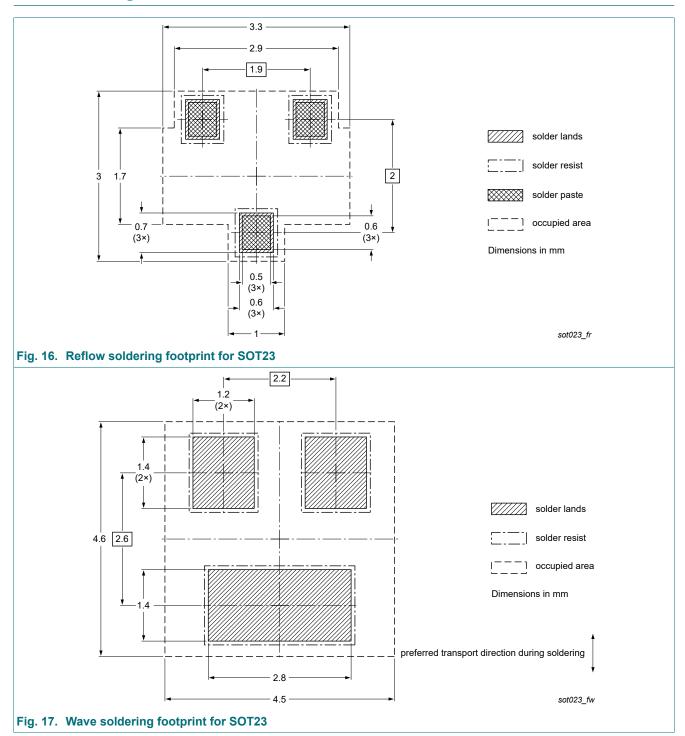


PMEG2005CT-Q

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13. Soldering



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2005CT-Q v.1	20230626	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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